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April 1st, 2010 Renesas Electronics Corporation

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DATA SHEET



BIPOLAR ANALOG INTEGRATED CIRCUIT

μ PC3224TB

5 V, SILICON MMIC WIDEBAND AMPLIFIER

DESCRIPTION

The μ PC3224TB is a silicon monolithic IC designed as IF amplifier for DBS tuners. This IC is manufactured using our 30 GHz f_{max} UHS0 (<u>Ultra High Speed Process</u>) silicon bipolar process.

FEATURES

• Wideband response : fu = 3.2 GHz TYP. @ 3 dB bandwidth

• Low current : Icc = 9.0 mA TYP.

• Power gain : GP = 21.5 dB TYP. @ f = 1.0 GHz

: $G_P = 21.5 \text{ dB TYP}$. @ f = 2.2 GHz

• Supply voltage : Vcc = 4.5 to 5.5 V • Port impedance : input/output 50Ω

APPLICATION

· IF amplifiers in DBS converters etc.

ORDERING INFORMATION

Part Number	Package	Marking	Supplying Form
μPC3224TB-E3	6-pin super minimold	СЗК	Embossed tape 8 mm wide 1, 2, 3 pins face the perforation side of tape Qty 3 kpcs/reel

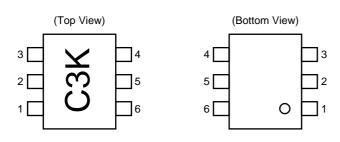
Remark To order evaluation samples, contact your nearby sales office.

Part number for sample order: μ PC3224TB

Caution Observe precautions when handling because these devices are sensitive to electrostatic discharge.

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PIN CONNECTIONS



Pin No.	Pin Name
1	INPUT
2	GND
3	GND
4	OUTPUT
5	GND
6	Vcc

PRODUCT LINE-UP OF 5 V-BIAS SILICON MMIC MEDIUM WIDEBAND AMPLIFIER (Ta = +25°C, f = 1 GHz, Vcc = Vout = 5.0 V, Zs = ZL = 50 Ω)

Part No.	f _u (GHz)	Po (sat) (dBm)	G _P (dB)	NF (dB)	Icc (mA)	Package	Marking
μPC2711TB	2.9	+1.0	13	5.0	12	6-pin super minimold	C1G
μPC2712TB	2.6	+3.0	20	4.5	12		C1H
μ PC3215TB Note	2.9	+3.5	20.5	2.3	14		СЗН
μPC3224TB	3.2	+4.0	21.5	4.3	9.0		СЗК

Note μ PC3215TB is f = 1.5 GHz

Remark Typical performance. Please refer to ELECTRICAL CHARACTERISTICS in detail.

PIN EXPLANATIONS

PIN No.	Pin Name	Applied Voltage (V)	Pin Voltage (V) Note	Function and Applications
1	INPUT	-	0.91	Signal input pin. A internal matching circuit, configured with resistors, enables 50 Ω connection over a wide band. A multi-feedback circuits is designed to cancel the deviations of hree and resistance. This pin must be coupled to signal source with capacitor for DC cut.
4	OUTPUT	-	4.42	Signal output pin. A internal matching circuit, configured with resistors, enables 50 Ω connection over a wide band. This pin must be coupled to next stage with capacitor for DC cut.
6	Vcc	4.5 to 5.5	-	Power suplly pin. This pin should be externally equipped with bypass capacitor to minimize its impedance.
2 3 5	GND	0	-	Ground pin. This pin should be connected to system ground with minimum inductance. Ground pattern on the board should be formed as wide as possible. All the ground pins must be connected together with wide ground pattern to decrease impedance difference.

Note Pin Voltage is measured at Vcc = 5.0 V

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ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Conditions	Ratings	Unit
Supply Voltage	Vcc	T _A = +25°C	6.0	V
Total Circuit Current	Icc	T _A = +25°C	25	mA
Power Dissipation	Po	$T_A = +85^{\circ}C$ Note	270	mW
Operating Ambient Temperature	TA		-40 to +85	°C
Storage Temperature	T _{stg}		-55 to +150	°C
Input Power	Pin	T _A = +25°C	+10	dBm

Note Mounted on double-sided copper-clad $50 \times 50 \times 1.6$ mm epoxy glass PWB

RECOMMENDED OPERATING RANGE

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Supply Voltage	Vcc		4.5	5.0	5.5	V
Operating Ambient Temperature	TA		-40	+25	+85	°C

ELECTRICAL CHARACTERISTICS (Ta = +25°C, Vcc = 5.0 V, Zs = ZL = 50 Ω)

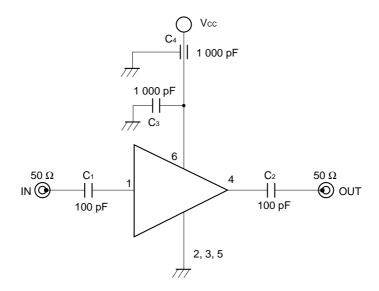
Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Circuit Current	lcc	No input signal	7.0	9.0	12.0	mA
Power Gain	G₽	f = 1.0 GHz, Pin = -30 dBm	19.0	21.5	24.0	dB
		f = 2.2 GHz, Pin = -30 dBm	18.5	21.5	24.5	
Saturated Output Power	Po (sat)	f = 1.0 GHz, Pin = -5 dBm	+1.5	+4.0	_	dBm
		f = 2.2 GHz, Pin = -5 dBm	-1.5	+1.5	_	
Gain 1 dB Compression Output	Po (1 dB)	f = 1.0 GHz	-6.5	-3.5	_	dBm
Power		f = 2.2 GHz	-8.5	-5.5	-	
Noise Figure	NF	f = 1.0 GHz	_	4.3	5.8	dB
		f = 2.2 GHz	-	4.3	5.8	
Upper Limit Operating Frequency	fu	3 dB down below flat gain at f = 0.1 GHz	2.8	3.2	-	GHz
Isolation	ISL	f = 1.0 GHz, Pin = -30 dBm	35.0	40.0	-	dB
		f = 2.2 GHz, Pin = -30 dBm	37.0	42.0	_	
Input Return Loss	RLin	f = 1.0 GHz, Pin = -30 dBm	9.0	12.0	_	dB
		f = 2.2 GHz, Pin = -30 dBm	10.0	14.0	_	
Output Return Loss	RLout	f = 1.0 GHz, Pin = -30 dBm	11.0	17.0	_	dB
		f = 2.2 GHz, Pin = -30 dBm	8.0	12.0	_	
Gain Flatness	⊿Gp	f = 0.1 to 2.2 GHz	-	±0.8	-	dB

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OTHER CHARACTERISTICS, FOR REFERENCE PURPOSES ONLY (Ta = +25°C, Vcc = 5.0 V, Zs = ZL = 50 Ω)

Parameter	Symbol	Test Conditions	Reference Value	Unit
Output Intercept Point	OIP ₃	f = 1.0 GHz	+7.0	dBm
		f = 2.2 GHz	+5.5	

TEST CIRCUIT



The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

COMPONENTS OF TEST CIRCUIT FOR

MEASURING ELECTRICAL CHARACTERISTICS

	Туре	Value
C ₁ , C ₂	Chip Capacitor	100 pF
С3	Chip Capacitor	1 000 pF
C ₄	Feed-through Capacitor	1 000 pF

CAPACITORS FOR THE Vcc, INPUT AND OUTPUT PINS

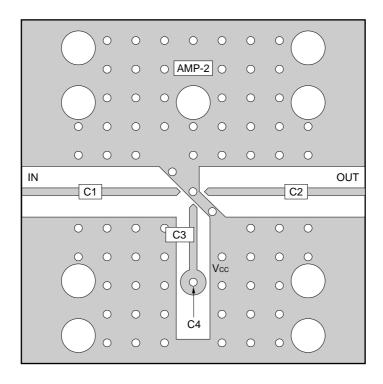
Capacitors of 1000 pF are recommendable as the bypass capacitor for the Vcc pin and the coupling capacitors for the input and output pins.

The bypass capacitor connected to the Vcc pin is used to minimize ground impedance of Vcc pin. So, stable bias can be supplied against Vcc fluctuation.

The coupling capacitors, connected to the input and output pins, are used to cut the DC and minimize RF serial impedance. Their capacitances are therefore selected as lower impedance against a 50 Ω load. The capacitors thus perform as high pass filters, suppressing low frequencies to DC.

To obtain a flat gain from 100 MHz upwards, 1 000 pF capacitors are used in the test circuit. In the case of under 10 MHz operation, increase the value of coupling capacitor such as 10 000 pF. Because the coupling capacitors are determined by equation, $C = 1/(2 \pi Rfc)$.

ILLUSTRATION OF THE TEST CIRCUIT ASSEMBLED ON EVALUATION BOARD



COMPONENT LIST

	Value
C ₁ , C ₂	100 pF
C ₃ , C ₄	1 000 pF

Notes

1. $30 \times 30 \times 0.4$ mm double sided copper clad polyimide board.

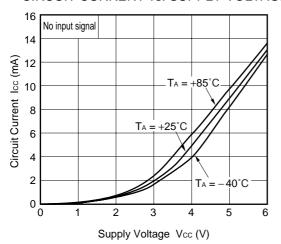
2. Back side: GND pattern

3. Solder plated on pattern

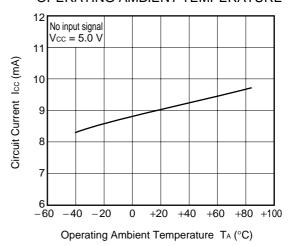
4. oO: Through holes

TYPICAL CHARACTERISTICS (TA = +25°C, unless otherwise specified)

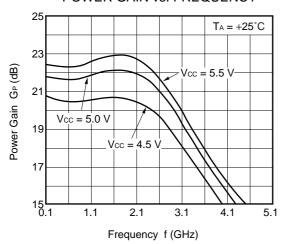
CIRCUIT CURRENT vs. SUPPLY VOLTAGE



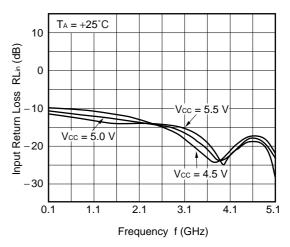
CIRCUIT CURRENT vs. OPERATING AMBIENT TEMPERATURE



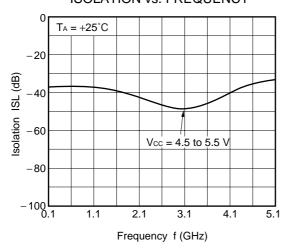
POWER GAIN vs. FREQUENCY



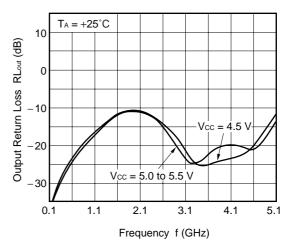
INPUT RETURN LOSS vs. FREQUENCY



ISOLATION vs. FREQUENCY

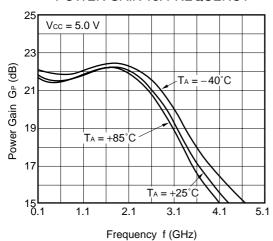


OUTPUT RETURN LOSS vs. FREQUENCY

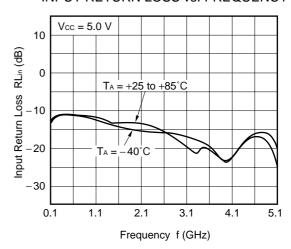


Remark The graphs indicate nominal characteristics.

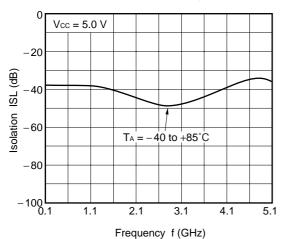
POWER GAIN vs. FREQUENCY



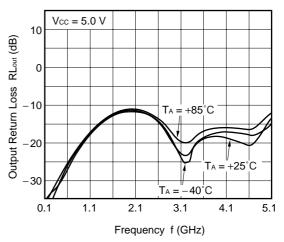
INPUT RETURN LOSS vs. FREQUENCY



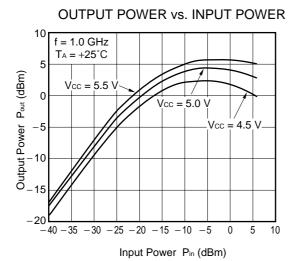
ISOLATION vs. FREQUENCY

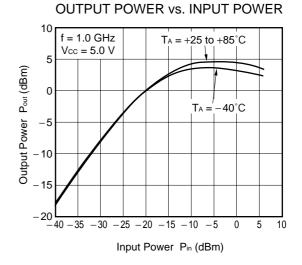


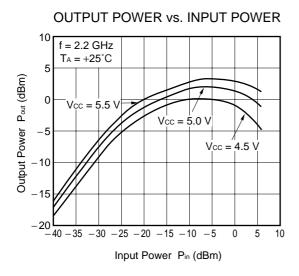
OUTPUT RETURN LOSS vs. FREQUENCY

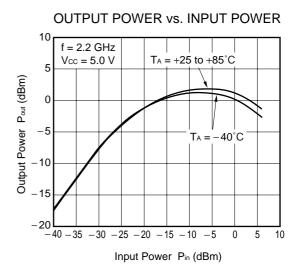


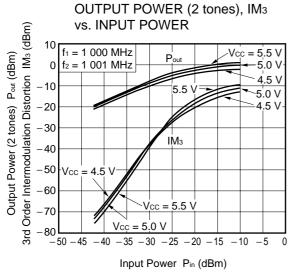
Remark The graphs indicate nominal characteristics.

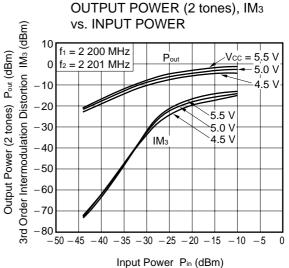








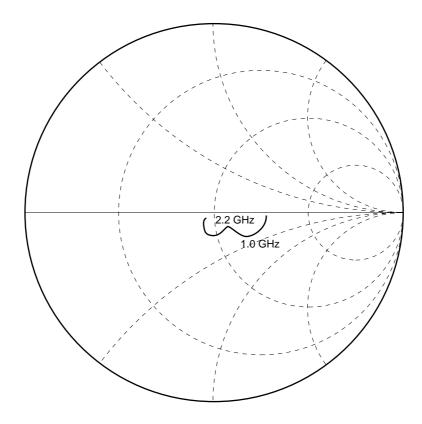




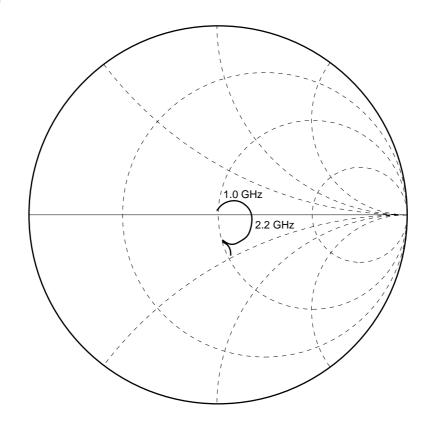
Remark The graphs indicate nominal characteristics.

S-PARAMETERS (Ta = +25°C, Vcc = 5.0 V)

S₁₁-FREQUENCY



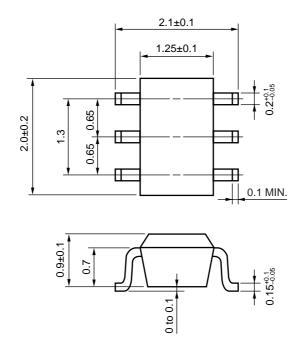
S₂₂-FREQUENCY



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PACKAGE DIMENSIONS

6-PIN SUPER MINIMOLD (UNIT: mm)



NOTES ON CORRECT USE

- (1) Observe precautions for handling because of electro-static sensitive devices.
- (2) Form a ground pattern as widely as possible to minimize ground impedance (to prevent undesired oscillation). All the ground pins must be connected together with wide ground pattern to decrease impedance difference.
- (3) The bypass capacitor should be attached to Vcc line.
- (4) The DC cut capacitor must be each attached to input and output pin.

RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions		Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) Time at peak temperature Time at temperature of 220°C or higher Preheating time at 120 to 180°C Maximum number of reflow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 60 seconds or less : 120±30 seconds : 3 times : 0.2%(Wt.) or below	IR260
Wave Soldering	Peak temperature (molten solder temperature) Time at peak temperature Preheating temperature (package surface temperature) Maximum number of flow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 120°C or below : 1 time : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (pin temperature) Soldering time (per side of device) Maximum chlorine content of rosin flux (% mass)	: 350°C or below : 3 seconds or less : 0.2%(Wt.) or below	HS350

Caution Do not use different soldering methods together (except for partial heating).

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NEC μ PC3224TB

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NEC Compound Semiconductor Devices, Ltd. http://www.ncsd.necel.com/

E-mail: salesinfo@ml.ncsd.necel.com (sales and general) techinfo@ml.ncsd.necel.com (technical)

5th Sales Group, Sales Division TEL: +81-44-435-1588 FAX: +81-44-435-1579

NEC Compound Semiconductor Devices Hong Kong Limited

E-mail: ncsd-hk@elhk.nec.com.hk (sales, technical and general)

Hong Kong Head Office TEL: +852-3107-7303 FAX: +852-3107-7309
Taipei Branch Office TEL: +886-2-8712-0478 FAX: +886-2-2545-3859
Korea Branch Office TEL: +82-2-558-2120 FAX: +82-2-558-5209

NEC Electronics (Europe) GmbH http://www.ee.nec.de/

TEL: +49-211-6503-0 FAX: +49-211-6503-1327

California Eastern Laboratories, Inc. http://www.cel.com/

TEL: +1-408-988-3500 FAX: +1-408-988-0279